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REF3012 REF3025 REF3030 REF3033 REF3040

SBVS032F - MARCH 2002 - REVISED AUGUST 2008

50ppm/°C Max, 50μA in SOT23-3 CMOS VOLTAGE REFERENCE

FEATURES

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● MicroSIZE PACKAGE: SOT23-3

LOW DROPOUT: 1mV

HIGH OUTPUT CURRENT: 25mA

• HIGH ACCURACY: 0.2%

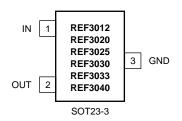
LOW I_Q: 50μA max

• EXCELLENT SPECIFIED DRIFT PERFORMANCE:

50ppm/°C (max) from 0°C to +70°C 75ppm/°C (max) from -40°C to +125°C

APPLICATIONS

- PORTABLE, BATTERY-POWERED EQUIPMENT
- DATA ACQUISITION SYSTEMS
- MEDICAL EQUIPMENT
- HAND-HELD TEST EQUIPMENT



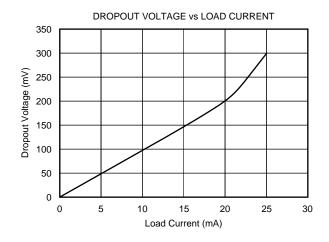
DESCRIPTION

The REF30xx is a precision, low power, low voltage dropout voltage reference family available in a tiny SOT23-3.

The REF30xx small size and low power consumption ($50\mu A$ max) make it ideal for portable and battery-powered applications. The REF30xx does not require a load capacitor.

Unloaded, the REF30xx can be operated with supplies within 1mV of output voltage. All models are specified for the wide temperature range, -40° C to $+125^{\circ}$ C.

PRODUCT	VOLTAGE (V)
REF3012	1.25
REF3020	2.048
REF3025	2.5
REF3030	3.0
REF3033	3.3
REF3040	4.096





Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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ABSOLUTE MAXIMUM RATINGS(1)

Supply Voltage, V+ to V	7.0V
Output Short-Circuit ⁽²⁾	
Operating Temperature	40°C to +125°C
Storage Temperature	65°C to +150°C
Junction Temperature	+150°C
Lead Temperature (soldering, 10s)	+300°C

NOTES: (1) Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. These are stress ratings only, and functional operation of the device at these, or any other conditions beyond those specified, is not implied. (2) Short circuit to ground.

ELECTROSTATIC DISCHARGE SENSITIVITY

This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

PACKAGE/ORDERING INFORMATION(1)

PRODUCT	PACKAGE-LEAD	PACKAGE DESIGNATOR	SPECIFIED TEMPERATURE RANGE	PACKAGE MARKING	ORDERING NUMBER	TRANSPORT MEDIA, QUANTITY
REF3012	SOT23-3	DBZ "	-40°C to +125°C	R30A "	REF3012AIDBZT REF3012AIDBZR	Tape and Reel, 250 Tape and Reel, 3000
REF3020	SOT23-3	DBZ "	–40°C to +125°C "	R30B "	REF3020AIDBZT REF3020AIDBZR	Tape and Reel, 250 Tape and Reel, 3000
REF3025	SOT23-3	DBZ "	–40°C to +125°C	R30C	REF3025AIDBZT REF3025AIDBZR	Tape and Reel, 250 Tape and Reel, 3000
REF3030	SOT23-3	DBZ "	–40°C to +125°C	R30F "	REF3030AIDBZRT REF3030AIDBZR	Tape and Reel, 250 Tape and Reel, 3000
REF3033	SOT23-3	DBZ "	–40°C to +125°C	R30D "	REF3033AIDBZT REF3033AIDBZR	Tape and Reel, 250 Tape and Reel, 3000
REF3040	SOT23-3	DBZ "	–40°C to +125°C "	R30E "	REF3040AIDBZT REF3040AIDBZR	Tape and Reel, 250 Tape and Reel, 3000

NOTE: (1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at www.ti.com.

ELECTRICAL CHARACTERISTICS

Boldface limits apply over the specified temperature range, $T_A = -40^{\circ}C$ to $+125^{\circ}C$.

At $T_A = +25$ °C, $I_{LOAD} = 0$ mA, $V_{IN} = 5$ V, unless otherwise noted.

				REF30xx							
PARAMETER		CONDITIONS	MIN	TYP	MAX	UNITS					
	REF3012 ⁽¹⁾ - 1.25V										
OUTPUT VOLTAGE Initial Accuracy	V _{OUT}		1.2475	1.25	1.2525 0.2	V %					
NOISE Output Voltage Noise Voltage Noise		f = 0.1Hz to 10Hz f = 10Hz to 10kHz		14 42		μVp-p μVrms					
LINE REGULATION		$1.8V \leq V_{IN} \leq 5.5V$		60	190	μV/V					
	•	REF3020 - 2.048	•								
OUTPUT VOLTAGE Initial Accuracy	V _{OUT}		2.044	2.048	2.052 0.2	V %					
NOISE Output Voltage Noise Voltage Noise		f = 0.1Hz to 10Hz f = 10Hz to 10kHz		23 65		μVp-p μVrms					
LINE REGULATION		V_{REF} + 50mV $\leq V_{IN} \leq 5.5V$		110	290	μV/V					
		REF3025 - 2.5V									
OUTPUT VOLTAGE Initial Accuracy	V _{OUT}		2.495	2.50	2.505 0.2	V %					
NOISE Output Voltage Noise Voltage Noise		f = 0.1Hz to 10Hz f = 10Hz to 10kHz		28 80		μVp-p μVrms					
LINE REGULATION		V_{REF} + 50mV $\leq V_{IN} \leq 5.5V$		120	325	μV/V					

ELECTRICAL CHARACTERISTICS

Boldface limits apply over the specified temperature range, $T_A = -40^{\circ}C$ to $+125^{\circ}C$.

At $T_A = +25^{\circ}C$, $I_{LOAD} = 0$ mA, $V_{IN} = 5$ V, unless otherwise noted.

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
	REF3030 - 3.0V	,			
OUTPUT VOLTAGE V _{OUT}		2.994	3.0	3.006 0.2	V %
NOISE Output Voltage Noise Voltage Noise	f = 0.1Hz to 10Hz f = 10Hz to 10kHz		33 94		μVp-p μVrms
LINE REGULATION	V_{REF} + 50mV $\leq V_{IN} \leq 5.5V$		120	375	μV/V
<u> </u>	REF3033 - 3.3V	'			
OUTPUT VOLTAGE V _{OUT}		3.294	3.30	3.306 0.2	V %
NOISE Output Voltage Noise Voltage Noise	f = 0.1Hz to 10Hz f = 10Hz to 10kHz		36 105		μVp-p μVrms
LINE REGULATION	V_{REF} + 50mV $\leq V_{IN} \leq 5.5V$		130	400	μV/V
<u> </u>	REF3040 - 4.096V				
OUTPUT VOLTAGE V _{OUT}		4.088	4.096	4.104 0.2	V %
NOISE Output Voltage Noise Voltage Noise	f = 0.1Hz to 10Hz f = 10Hz to 10kHz		45 128		μVp-p μVrms
LINE REGULATION	V_{REF} + 50mV $\leq V_{IN} \leq 5.5V$		160	410	μV/V
REF3012, REF	3020, REF3025, REF3030, REF	-3033, REF304	0		
OUTPUT VOLTAGE TEMP DRIFT ⁽²⁾ dV _{OUT} /dT	$0^{\circ}C \le T_{A} \le +70^{\circ}C$ $-30^{\circ}C \le T_{A} \le +85^{\circ}C$ $-40^{\circ}C \le T_{A} \le +85^{\circ}C$ $-40^{\circ}C \le T_{A} \le +125^{\circ}C$		20 28 30 35	50 60 65 75	ppm/°C ppm/°C ppm/°C ppm/°C
LONG-TERM STABILITY	0-1000h 1000-2000h		24 15		ppm ppm
LOAD REGULATION ⁽³⁾ dV _{OUT} /dI _{LOAD}	$0mA < I_{LOAD} < 25mA,$ $V_{IN} = V_{REF} + 500mV^{(1)}$		3	100	μV/mA
THERMAL HYSTERESIS ⁽⁴⁾ dT			25	100	ppm
DROPOUT VOLTAGE V _{IN} - V _{OUT}			1	50	mV
SHORT-CIRCUIT CURRENT I _{SC}			45		mA
TURN ON SETTLING TIME	to 0.1% at $V_{IN} = 5V$ with $C_L = 0$		120		μs
POWER SUPPLY Voltage V _S	$I_L = 0$	V _{REF} + 0.001 ⁽⁵⁾		5.5	V
Over Temperature Quiescent Current I _Q	$-40^{\circ}\text{C} \leq \text{T}_{\text{A}} \leq +125^{\circ}\text{C}$	V _{REF} + 0.05	42	5.5 50	V μΑ
Over Temperature	$-40^{\circ}\text{C} \leq \text{T}_{\text{A}} \leq +125^{\circ}\text{C}$			59	μ Α
TEMPERATURE RANGE Specified Range Operating Range Storage Range Thermal Resistance		-40 -40 -65		+125 +125 +150	ဂိ ဂိ ဂိ
SOT23-3 Surface-Mount θ_{JC} θ_{JA}			110 336		°C/W °C/W

NOTES: (1) Minimum supply voltage for REF3012 is 1.8V.

⁽⁵⁾ For $I_L > 0$, see Typical Characteristic curves.



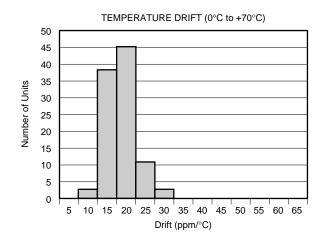
⁽²⁾ Box Method used to determine over temperature drift.

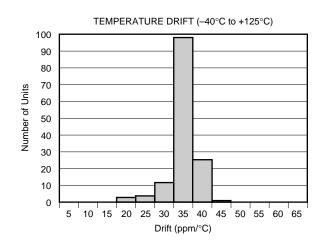
⁽³⁾ Typical value of load regulation reflects measurements using a force and sense contacts, see text Load Regulation.

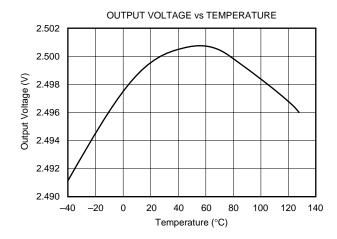
⁽⁴⁾ Thermal hysteresis procedure is explained in more detail in Applications Information section of data sheet.

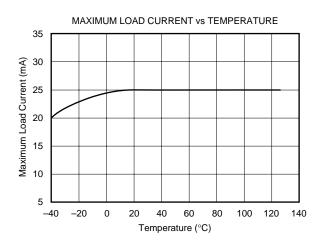
TYPICAL CHARACTERISTICS

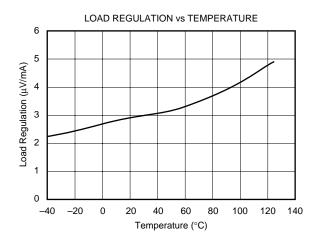
At $T_A = +25$ °C, $V_{IN} = +5$ V power supply, REF3025 is used for typical characteristics, unless otherwise noted.

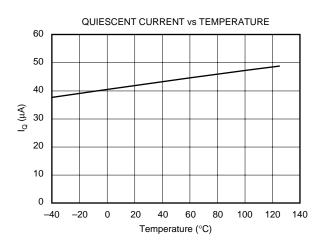






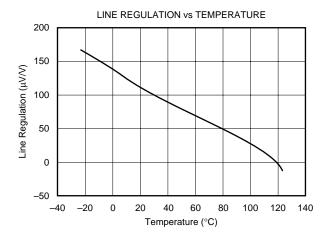


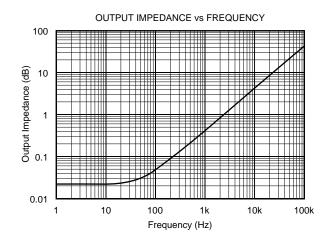


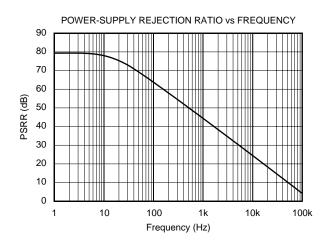


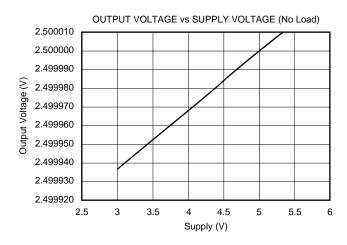
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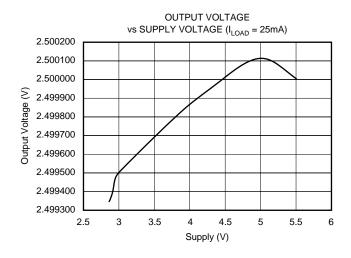
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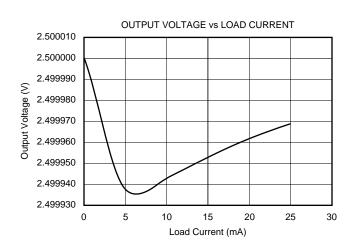






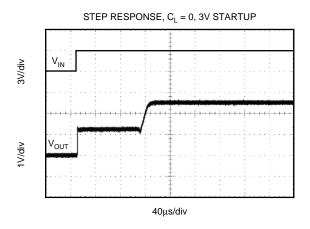


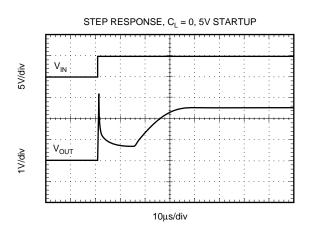


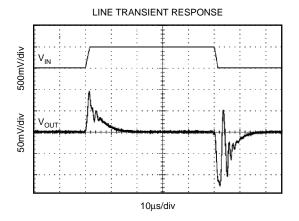


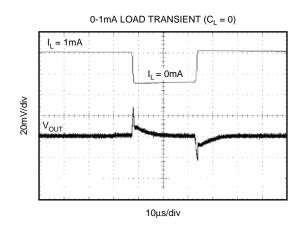
TYPICAL CHARACTERISTICS (Cont.)

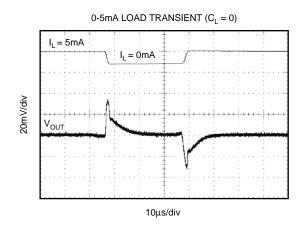
At $T_A = +25^{\circ}C$, $V_{IN} = +5V$ power supply, REF3025 is used for typical characteristics, unless otherwise noted.

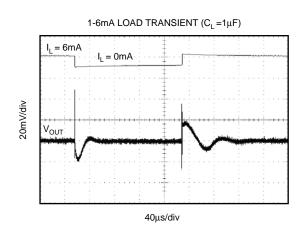






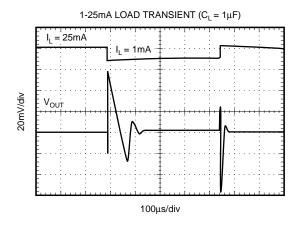


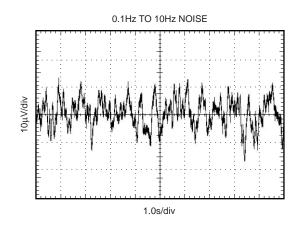


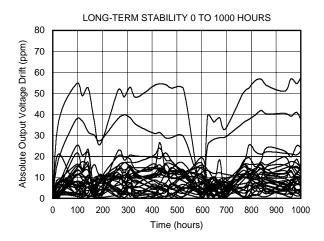


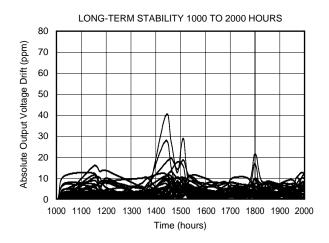
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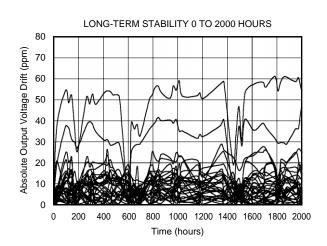
At $T_A = +25$ °C, $V_{IN} = +5V$ power supply, REF3025 is used for typical characteristics, unless otherwise noted.











THEORY OF OPERATION

The REF30xx is a series, CMOS, precision bandgap voltage reference. Its basic topology is shown in Figure 1. The transistors Q_1 and Q_2 are biased such that the current density of Q_1 is greater than that of Q_2 . The difference of the two base-emitter voltages, $Vbe_1 - Vbe_2$, has a positive temperature coefficient and is forced across resistor R_1 . This voltage is gained up and added to the base-emitter voltage of Q_2 , which has a negative coefficient. The resulting output voltage is virtually independent of temperature. The curvature of the bandgap voltage, as seen in the typical curve, "Output Voltage vs Temperature," is due to the slightly nonlinear temperature coefficient of the base-emitter voltage of Q_2 .

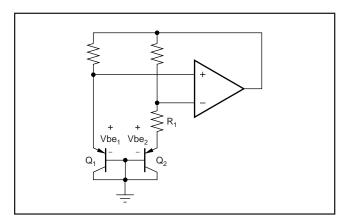


FIGURE 1. Simplified Schematic of Bandgap Reference.

APPLICATION INFORMATION

For normal operation, the REF30xx does not require a capacitor on the output. If a capacitive load is connected, special care must be taken with the combination of low equivalent series resistance (ESR) capacitors and high capacitance. This caution is especially true for low-output voltage devices; therefore, the REF3012 should only have a low-ESR capacitance of $10\mu F$ or less. Figure 2 shows the typical connections required for operation of the REF30xx. A supply bypass capacitor of $0.47\mu F$ is always recommended.

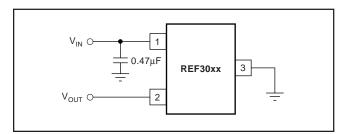


FIGURE 2. Typical Connections for Operating REF30xx.

SUPPLY VOLTAGE

The REF30xx family of references features an extremely low dropout voltage. With the exception of the REF3012, which has a minimum supply requirement of 1.8V, the REF30xx can be operated with a supply of only 1mV above the output voltage in an unloaded condition. For loaded conditions, a typical dropout voltage versus load is shown on the cover page.

The REF30xx features a low quiescent current, which is extremely stable over changes in both temperature and supply. The typical room temperature quiescent current is 42 μ A, and the maximum quiescent current over temperature is just 59 μ A. Additionally, the quiescent current typically changes less than 2.5 μ A over the entire supply range, as shown in Figure 3.

Supply voltages below the specified levels can cause the REF30xx to momentarily draw currents greater than the typical quiescent current. Using a power supply with a fast rising edge and low output impedance easily prevents this.

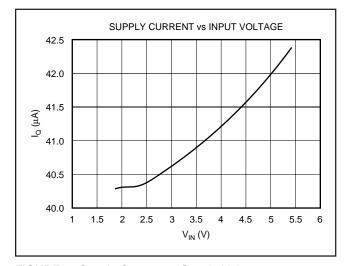


FIGURE 3. Supply Current vs Supply Voltage.

THERMAL HYSTERESIS

Thermal hysteresis for the REF30xx is defined as the change in output voltage after operating the device at 25°C, cycling the device through the specified temperature range, and returning to 25°C, and can be expressed as:

$$V_{HYST} = \left(\frac{abs|V_{PRE} - V_{POST}|}{V_{NOM}}\right) \bullet 10^{6} (ppm)$$

Where: $V_{HYST} = Calculated hysteresis$

V_{PRE} = Output voltage measured at 25°C pretemperature cycling

 V_{POST} = Output voltage measured when device has been operated at 25°C, cycled through specified range –40°C to +125°C and returned to operation at 25°C.

TEMPERATURE DRIFT

The REF30xx is designed to exhibit minimal drift error, defined as the change in output voltage over varying temperature. Using the "box" method of drift measurement, the REF30xx features a typical drift coefficient of 20ppm from 0°C to 70°C—the primary temperature range of use for many applications. For industrial temperature ranges of -40°C to 125°C, the REF30xx family drift increases to a typical value of 50ppm.



NOISE PERFORMANCE

The REF30xx generates noise less than $50\mu\text{Vp-p}$ between frequencies of 0.1Hz to 10Hz, and can be seen in the Typical Characteristic Curve "0.1 to 10Hz Voltage Noise." The noise voltage of the REF30xx increases with output voltage and operating temperature. Additional filtering may be used to improve output noise levels, although care should be taken to ensure the output impedance does not degrade AC performance.

LONG TERM STABILITY

Long term stability refers to the change of the output voltage of a reference over a period of months or years. This effect lessens as time progresses as is apparent by the long term stability curves. The typical drift value for the REF30xx is 24ppm from 0-1000 hours, and 15ppm from 1000-2000 hours. This parameter is characterized by measuring 30 units at regular intervals for a period of 2000 hours.

LOAD REGULATION

Load regulation is defined as the change in output voltage due to changes in load current. Load regulation for the REF30xx is measured using force and sense contacts as pictured in Figure 4. The force and sense lines tied to the contact area of the output pin reduce the impact of contact and trace resistance, resulting in accurate measurement of the load regulation contributed solely by the REF30xx. For applications requiring improved load regulation, force and sense lines should be used.

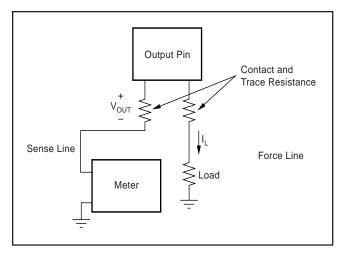


FIGURE 4. Accurate Load Regulation of REF30xx.

APPLICATION CIRCUITS

Negative Reference Voltage

For applications requiring a negative and positive reference voltage, the OPA703 and REF30xx can be used to provide a dual supply reference from a ±5V supply. Figure 5 shows the REF3025 used to provide a ±2.5V supply reference voltage. The low offset voltage and low drift of the OPA703 complement the low drift performance of the REF30xx to provide an accurate solution for split-supply applications.

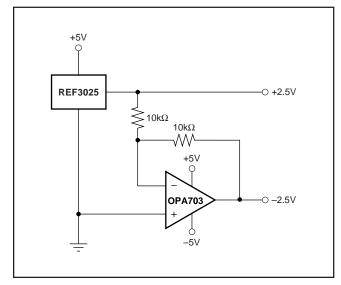


FIGURE 5. REF3025 Combined with OPA703 to Create Positive and Negative Reference Voltages.

DATA ACQUISITION

Often data acquisition systems require stable voltage references to maintain necessary accuracy. The REF30xx family features stability and a wide range of voltages suitable for most micro-controllers and data converters. Figure 6 and Figure 7 show two basic data acquisition systems.



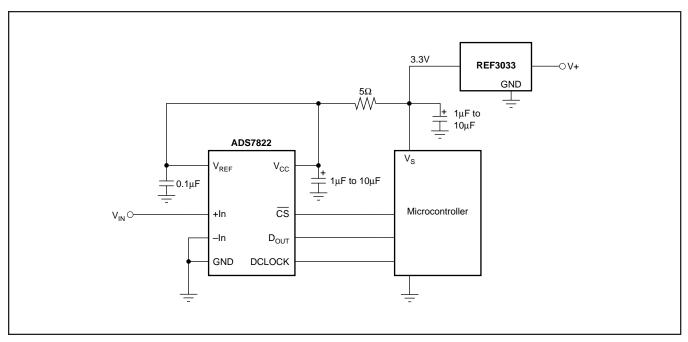


FIGURE 6. Basic Data Acquisition System 1.

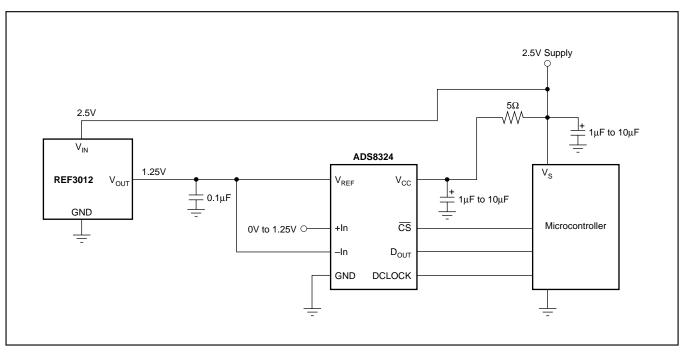


FIGURE 7. Basic Data Acquisition System 2.





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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp (3)
REF3012AIDBZR	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
REF3012AIDBZRG4	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
REF3012AIDBZT	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
REF3012AIDBZTG4	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
REF3020AIDBZR	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
REF3020AIDBZRG4	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
REF3020AIDBZT	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
REF3020AIDBZTG4	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
REF3025AIDBZR	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
REF3025AIDBZRG4	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
REF3025AIDBZT	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
REF3025AIDBZTG4	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
REF3030AIDBZR	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
REF3030AIDBZRG4	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
REF3030AIDBZT	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
REF3030AIDBZTG4	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
REF3033AIDBZR	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
REF3033AIDBZRG4	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
REF3033AIDBZT	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
REF3033AIDBZTG4	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
REF3040AIDBZR	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
REF3040AIDBZRG4	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
REF3040AIDBZT	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
REF3040AIDBZTG4	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

 $^{^{(1)}}$ The marketing status values are defined as follows:



PACKAGE OPTION ADDENDUM

www.ti.com 8-Jun-2009

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

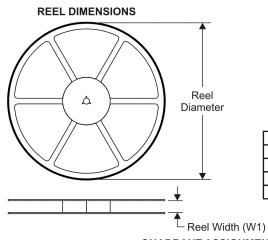
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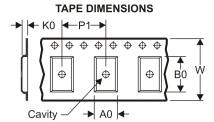
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

PACKAGE MATERIALS INFORMATION

www.ti.com 20-Jul-2010

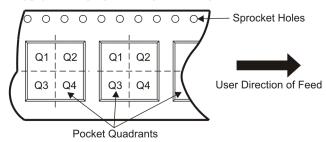
TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

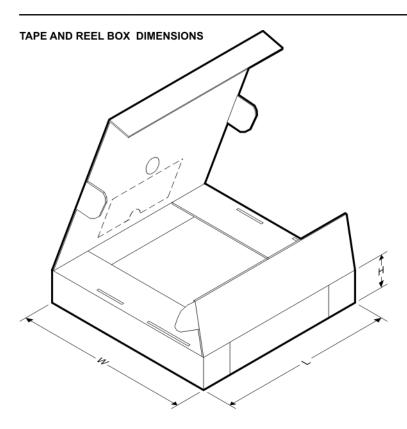
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
REF3012AIDBZR	SOT-23	DBZ	3	3000	179.0	8.4	3.15	2.95	1.22	4.0	8.0	Q3
REF3012AIDBZT	SOT-23	DBZ	3	250	179.0	8.4	3.15	2.95	1.22	4.0	8.0	Q3
REF3020AIDBZR	SOT-23	DBZ	3	3000	179.0	8.4	3.15	2.95	1.22	4.0	8.0	Q3
REF3020AIDBZT	SOT-23	DBZ	3	250	179.0	8.4	3.15	2.95	1.22	4.0	8.0	Q3
REF3025AIDBZR	SOT-23	DBZ	3	3000	179.0	8.4	3.15	2.95	1.22	4.0	8.0	Q3
REF3025AIDBZT	SOT-23	DBZ	3	250	179.0	8.4	3.15	2.95	1.22	4.0	8.0	Q3
REF3030AIDBZR	SOT-23	DBZ	3	3000	179.0	8.4	3.15	2.95	1.22	4.0	8.0	Q3
REF3030AIDBZT	SOT-23	DBZ	3	250	179.0	8.4	3.15	2.95	1.22	4.0	8.0	Q3
REF3033AIDBZR	SOT-23	DBZ	3	3000	179.0	8.4	3.15	2.95	1.22	4.0	8.0	Q3
REF3033AIDBZT	SOT-23	DBZ	3	250	179.0	8.4	3.15	2.95	1.22	4.0	8.0	Q3
REF3040AIDBZR	SOT-23	DBZ	3	3000	179.0	8.4	3.15	2.95	1.22	4.0	8.0	Q3
REF3040AIDBZT	SOT-23	DBZ	3	250	179.0	8.4	3.15	2.95	1.22	4.0	8.0	Q3

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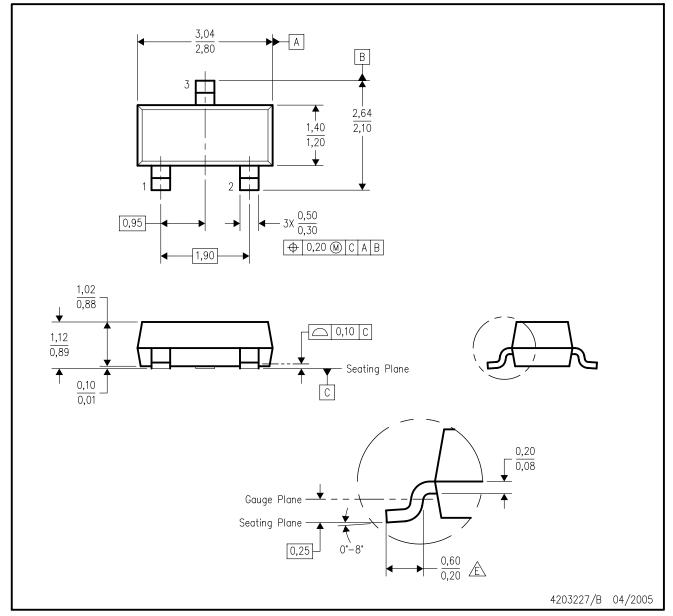


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
REF3012AIDBZR	SOT-23	DBZ	3	3000	203.0	203.0	35.0
REF3012AIDBZT	SOT-23	DBZ	3	250	203.0	203.0	35.0
REF3020AIDBZR	SOT-23	DBZ	3	3000	203.0	203.0	35.0
REF3020AIDBZT	SOT-23	DBZ	3	250	203.0	203.0	35.0
REF3025AIDBZR	SOT-23	DBZ	3	3000	203.0	203.0	35.0
REF3025AIDBZT	SOT-23	DBZ	3	250	203.0	203.0	35.0
REF3030AIDBZR	SOT-23	DBZ	3	3000	203.0	203.0	35.0
REF3030AIDBZT	SOT-23	DBZ	3	250	203.0	203.0	35.0
REF3033AIDBZR	SOT-23	DBZ	3	3000	203.0	203.0	35.0
REF3033AIDBZT	SOT-23	DBZ	3	250	203.0	203.0	35.0
REF3040AIDBZR	SOT-23	DBZ	3	3000	203.0	203.0	35.0
REF3040AIDBZT	SOT-23	DBZ	3	250	203.0	203.0	35.0

DBZ (R-PDSO-G3)

PLASTIC SMALL-OUTLINE



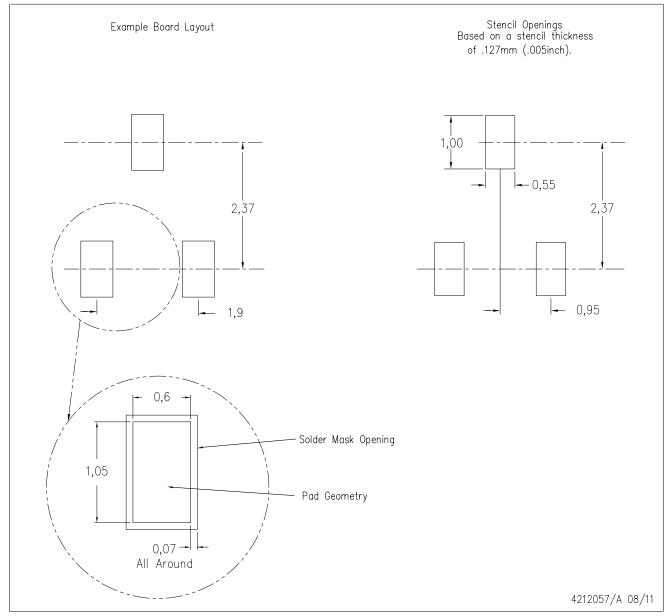
NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. Lead dimensions are inclusive of plating.
- D. Body dimensions are exclusive of mold flash and protrusion. Mold flash and protrusion not to exceed 0.25 per side.
- Falls within JEDEC TO-236 variation AB, except minimum foot length.



DBZ (R-PDSO-G3)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
- D. Publication IPC-7351 is recommended for alternate designs.
- E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.



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